

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

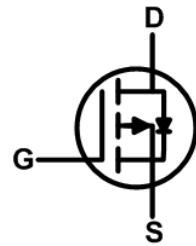
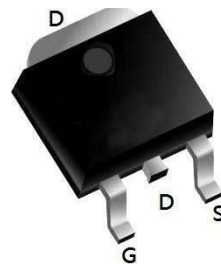
- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

Product Summary



BVDSS	RDSON	ID
-60V	20mΩ	-50A

TO252 Pin Configuration



Absolute Maximum Ratings (T_C= 25°C unless otherwise specified):

Symbol	Parameter		Value	Units
V _{DSS}	Drain-to-Source Voltage		-60	V
I _D	Continuous Drain Current	T _C = 25 °C	-50	A
	Continuous Drain Current	T _C = 100 °C	-25	A
I _{DM} ^{a1}	Pulsed Drain Current		-150	A
V _{GS}	Gate-to-Source Voltage		±20	V
P _D	Power Dissipation		95	W
E _{AS} ^{a2}	Single pulse avalanche energy		200	mJ
T _J , T _{STG}	Operating Junction and Storage Temperature Range		150, -55 to 150	°C
T _L	Maximum Temperature for Soldering		260	°C

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	1.32	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	60	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified):

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60	--	--	V
I_{DSS}	Drain to Source Leakage Current	$V_{DS} = -60V, V_{GS}= 0V$	--	--	1	μA
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS} = -20V$	--	--	100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = +20V$	--	--	-100	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	-1.8	-2.3	V
$R_{DS(ON)1}$	Drain-to-Source Resistance	On- $V_{GS}=-10V, I_D=-10A$	--	20.0	25.0	$m\Omega$
$R_{DS(ON)2}$	Drain-to-Source Resistance	On- $V_{GS}=-4.5V, I_D=-8A$	--	25.0	32.0	$m\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-5A$	--	20	--	S

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{GS}=0V$ $V_{DS}=-30V$ $f=1.0MHz$	--	1500	--	pF
C_{oss}	Output Capacitance		--	248	--	
C_{rss}	Reverse Transfer Capacitance		--	12	--	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}$ Open	--	8.0	--	Ω

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=-10A, R_L=3.0\Omega$ $V_{DS}= -30V$ $V_{GS}= -10V$ $R_G= 3\Omega$	--	15	--	ns
t_r	Rise Time		--	17	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	40	--	
t_f	Fall Time		--	45	--	
Q_g	Total Gate Charge	$V_{GS}=-10V$ $V_{DS}=-30V$ $I_D=-10A$	--	22	--	nC
Q_{gs}	Gate Source Charge		--	3.7	--	
Q_{gd}	Gate Drain Charge		--	3	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I_S	Diode Forward Current	$T_C=25^\circ C$	--	--	-50	A
I_{SM}	Diode Pulse Current		--	--	-150	A
V_{SD}	Diode Forward Voltage	$I_S=-5.0A, V_{GS}=0V$	--	--	-1.2	V

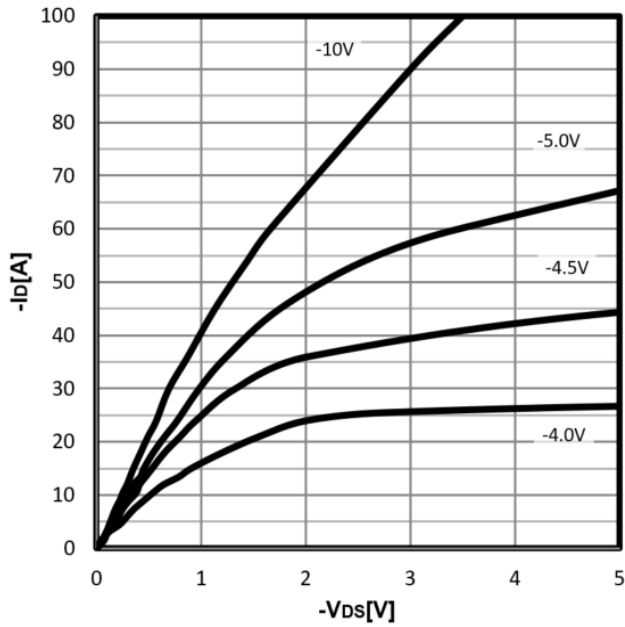
t_{rr}	Reverse Recovery time	$I_S=-10A, V_{DD}=-30V$ $dI/dt=100A/\mu s$	--	60	--	ns
Q_{rr}	Reverse Recovery Charge		--	105	--	nC

a¹: Repetitive rating; pulse width limited by maximum junction temperature

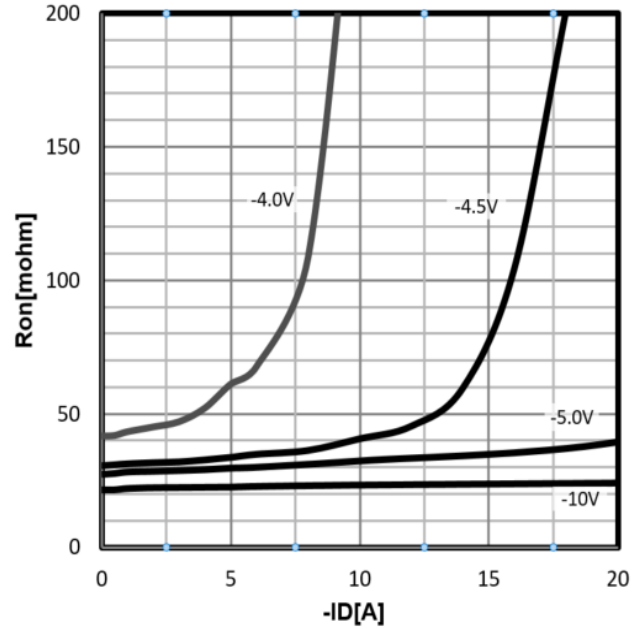
a²: $V_{DD} = -30V, L=1.0mH, R_G = 25\Omega, \text{Starting } T_j=25^\circ C$

Characteristics Curve:

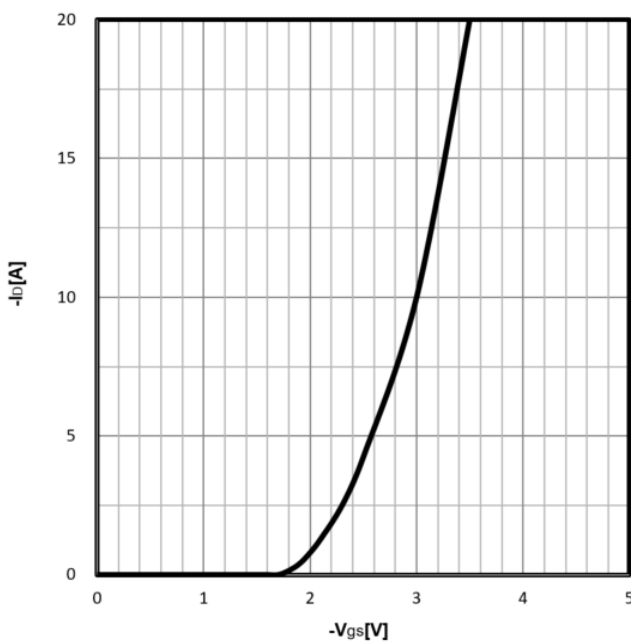
Typ. output characteristics
 $-I_D = f(-V_{DS})$



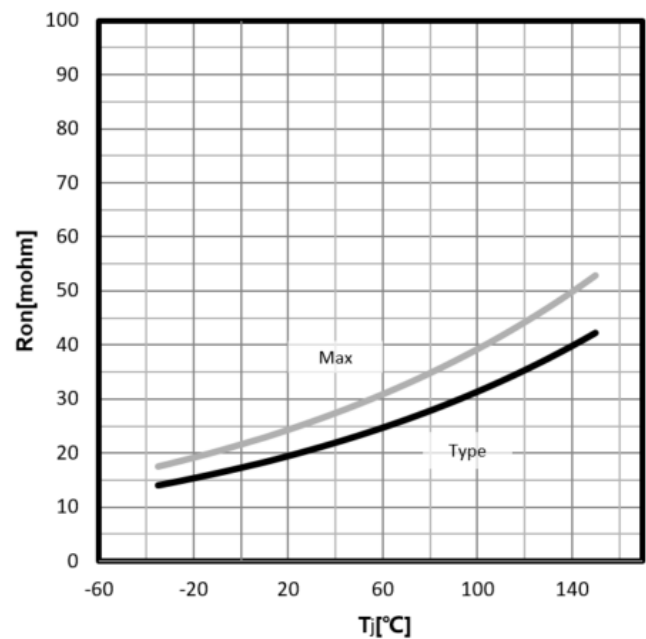
Typ. drain-source on resistance
 $R_{DS(on)} = f(-I_D)$



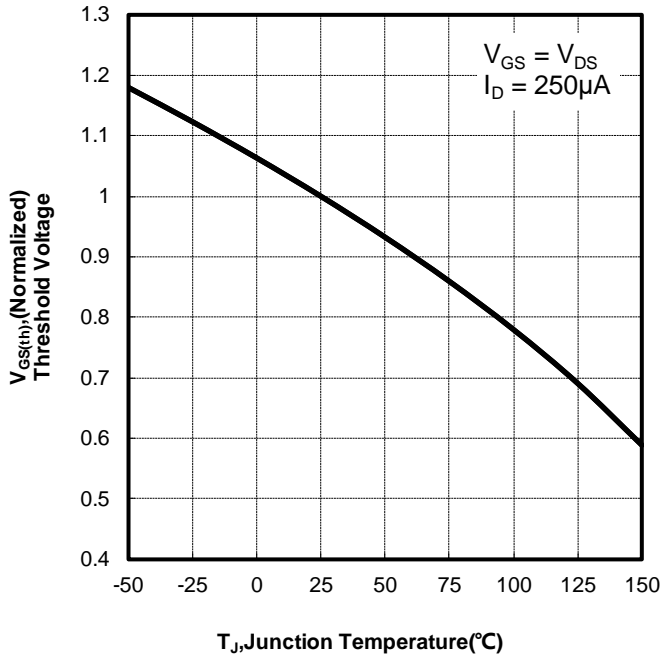
Typ. transfer characteristics
 $-I_D = f(-V_{GS})$



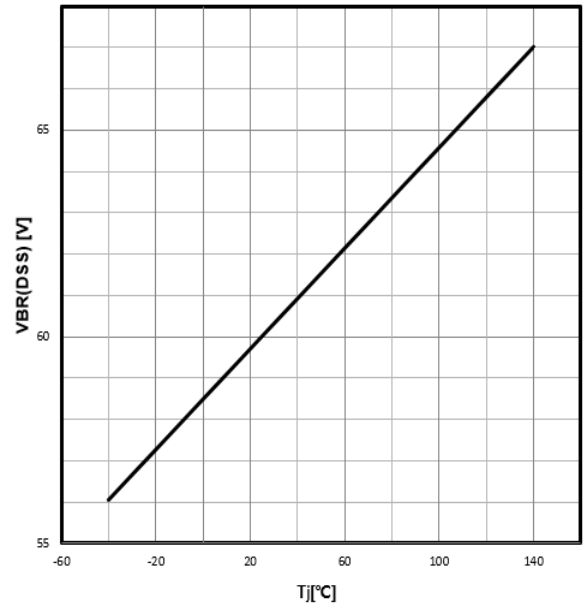
Drain-source on-state resistance
 $R_{DS(on)} = f(T_j); I_D = -10A; V_{GS} = -10V$



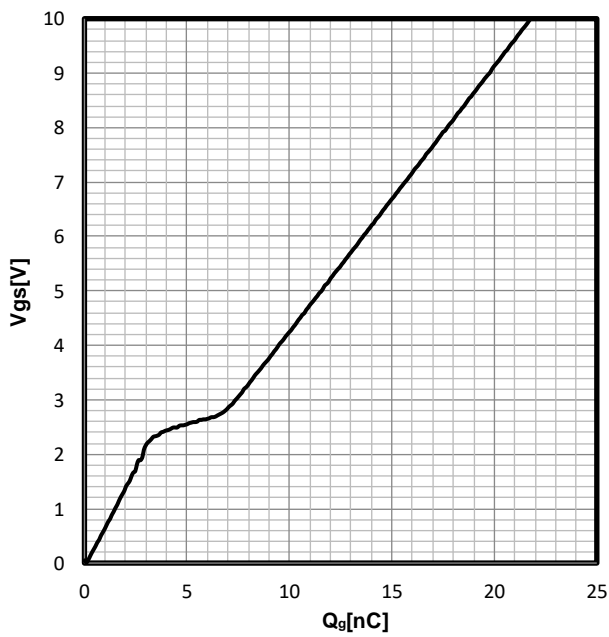
Gate Threshold Voltage
 $-V_{TH}=f(T_j); I_D=-250\mu A$



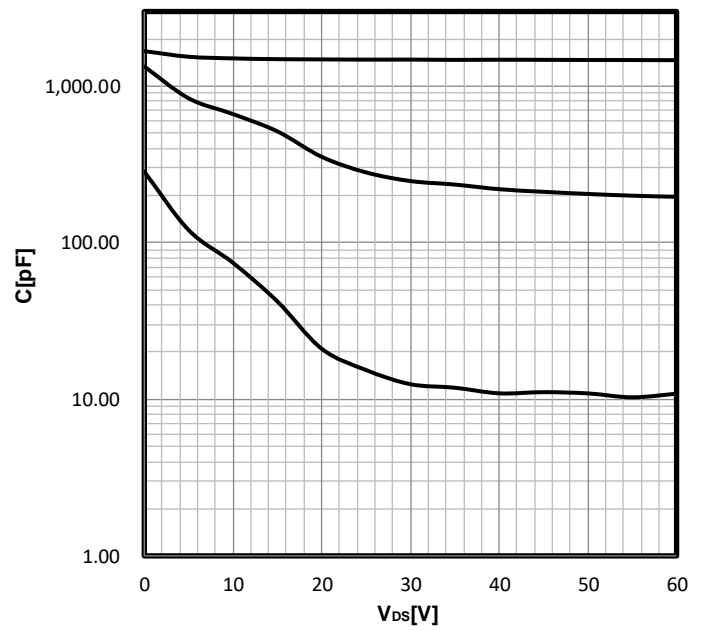
Drain-source breakdown voltage
 $-V_{BR(DSS)}=f(T_j); I_D=-250\mu A$



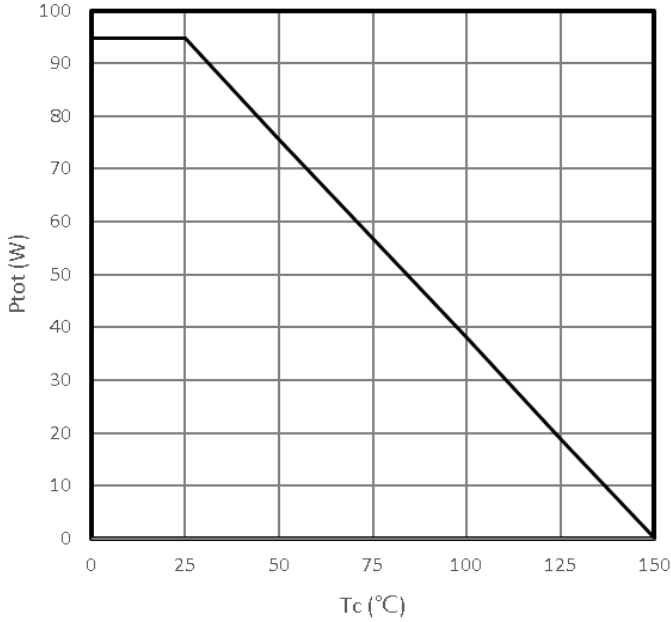
Typ. gate charge
 $V_{GS}=f(Q_{gate}); I_D=-5A$



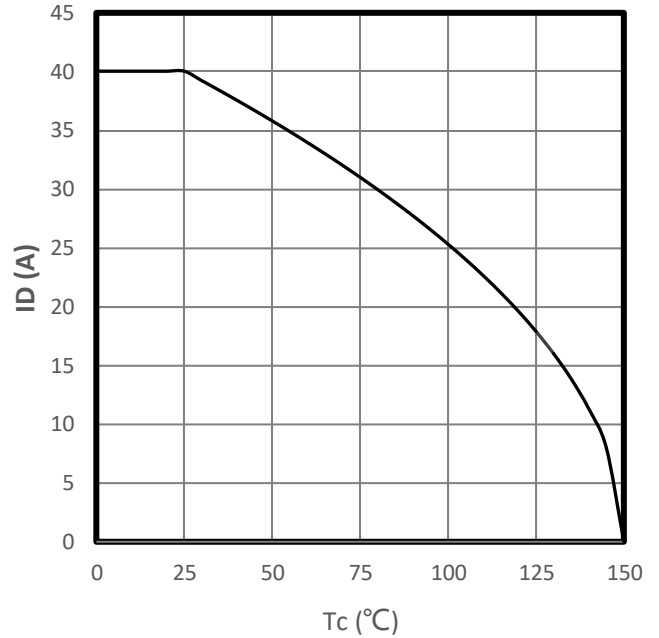
Typ. Capacitances
 $C=f(-V_{DS}); V_{GS}=0V; f=1MHz$



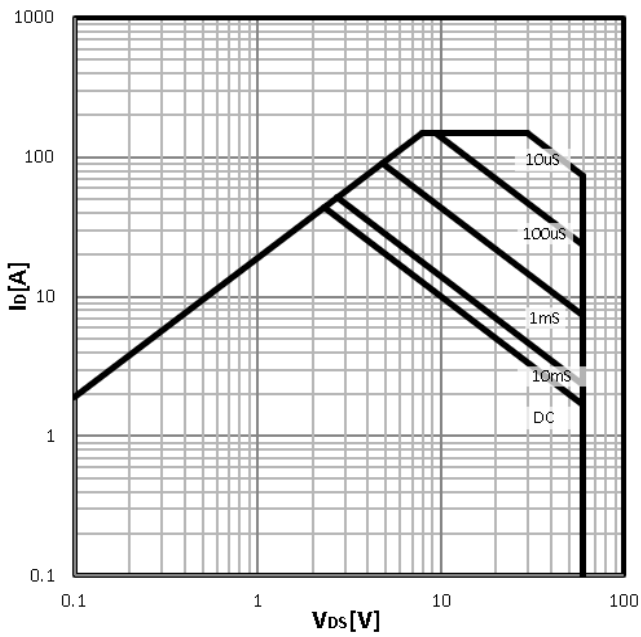
Power Dissipation
 $P_{tot}=f(T_c)$



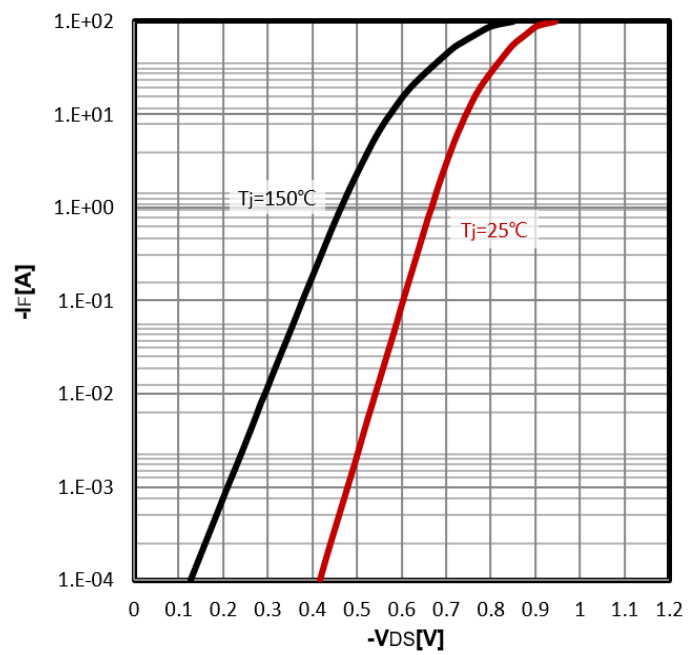
Maximum Drain Current
 $-I_D=f(T_c)$



Safe operating area
 $-I_D=f(-V_{DS})$

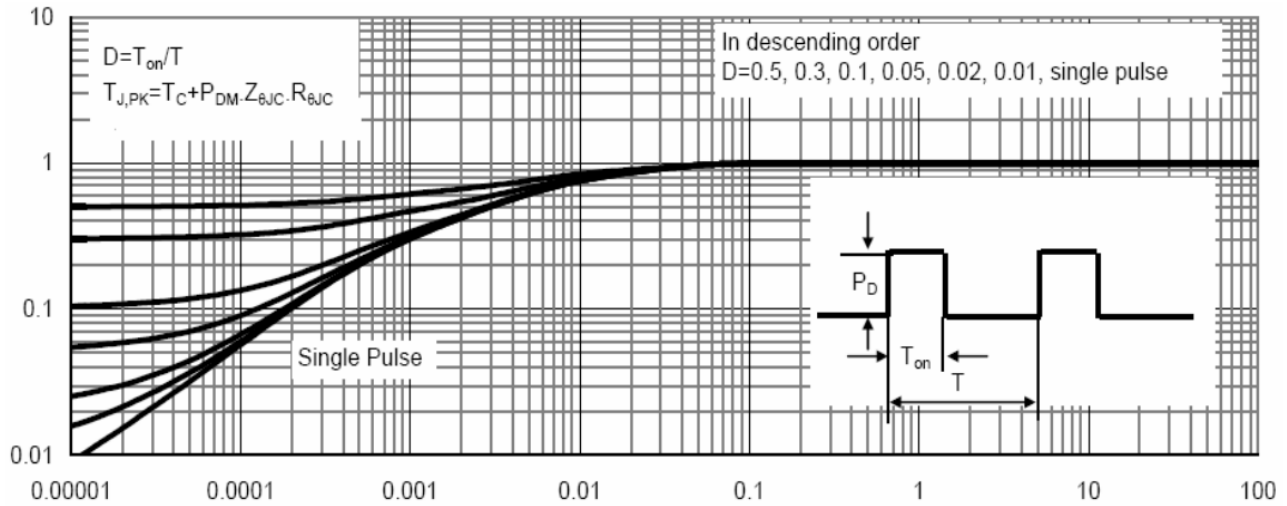


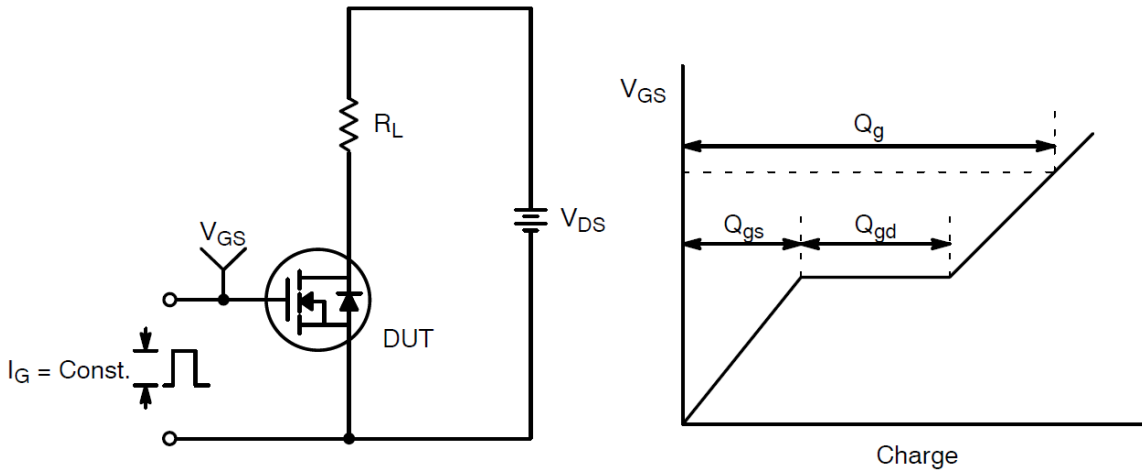
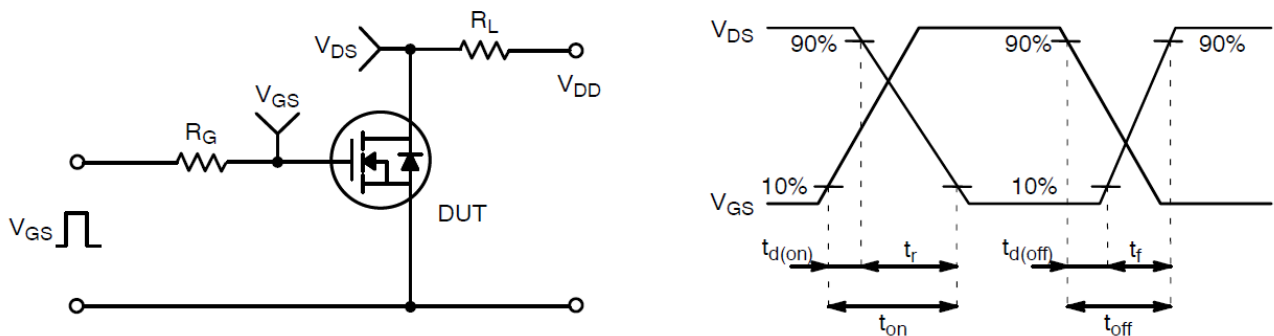
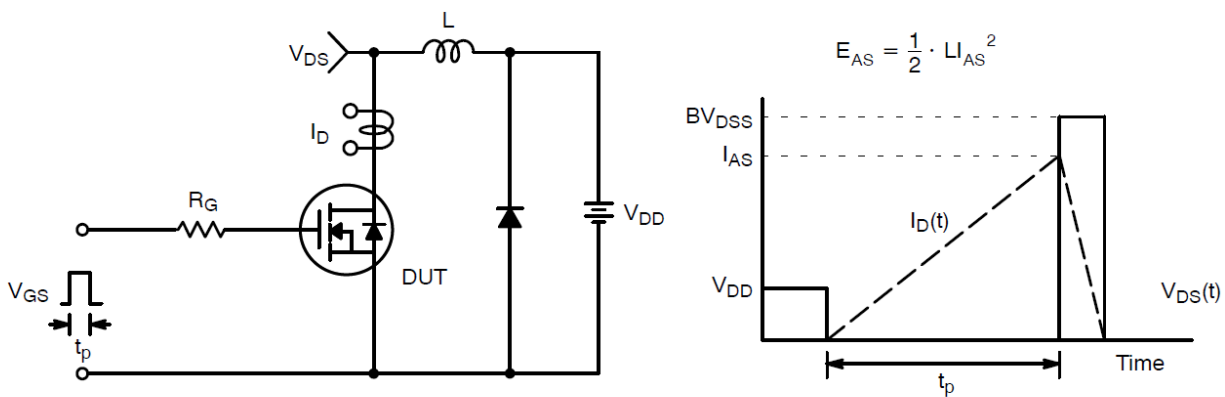
Body Diode Forward Voltage Variation
 $-I_F=f(-V_{DS})$



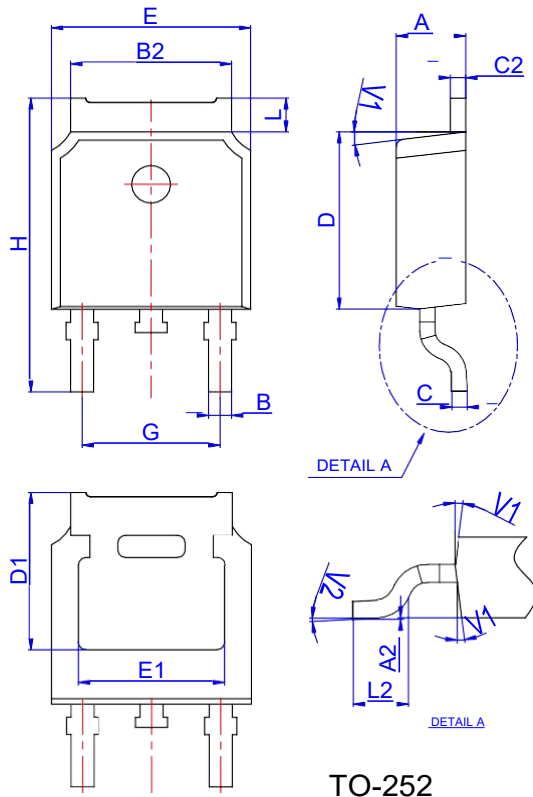
Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$



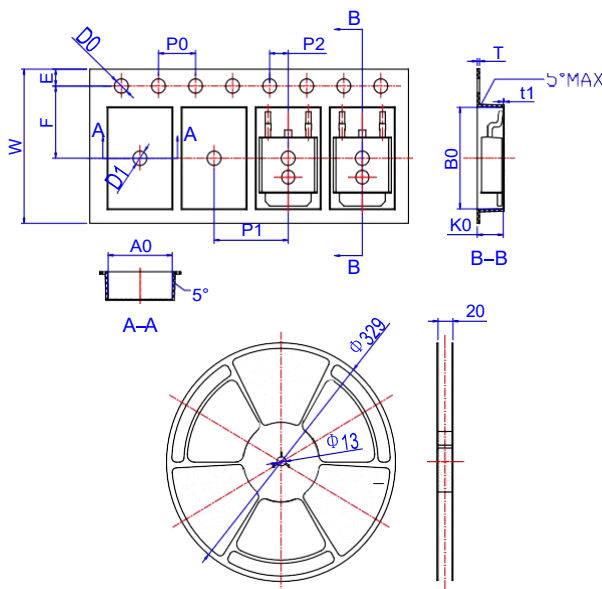
Test Circuit and Waveform:

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data TO 252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583